



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE9273QX V33		<b>Issued</b>		31. January 2019		
<b>MA#</b>		MA004737228						
<b>Package</b>		PG-VQFN-48-31		<b>Weight*</b>		129.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.989	3.07	3.07	30738	30738
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		552	
	non noble metal	iron	7439-89-6	1.433	1.10		11044	
wire	non noble metal	copper	7440-50-8	58.193	44.85	46.02	448418	460152
	non noble metal	copper	7440-50-8	0.609	0.47	0.47	4689	4689
	encapsulation	organic material	carbon black	1333-86-4	0.184	0.14		1414
	plastics	epoxy resin	-	7.770	5.99		59872	
		inorganic material	silicondioxide	60676-86-0	53.227	41.01	47.14	410149
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	20007	20007
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4730	4730
glue	plastics	epoxy resin	-	0.246	0.19		1897	
		noble metal	silver	7440-22-4	0.824	0.64	0.83	6352
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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